



SOT1194-1

DFN1010C-4: plastic thermal enhanced ultra thin small outline package; no leads; 4 terminals

10 June 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFN1010C-4
Package type industry code	DFN1010C-4
Package style descriptive code	HUSON (thermal enhanced ultra thin small outline; no leads)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	---
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	25-1-2011

Table 1. Package summary

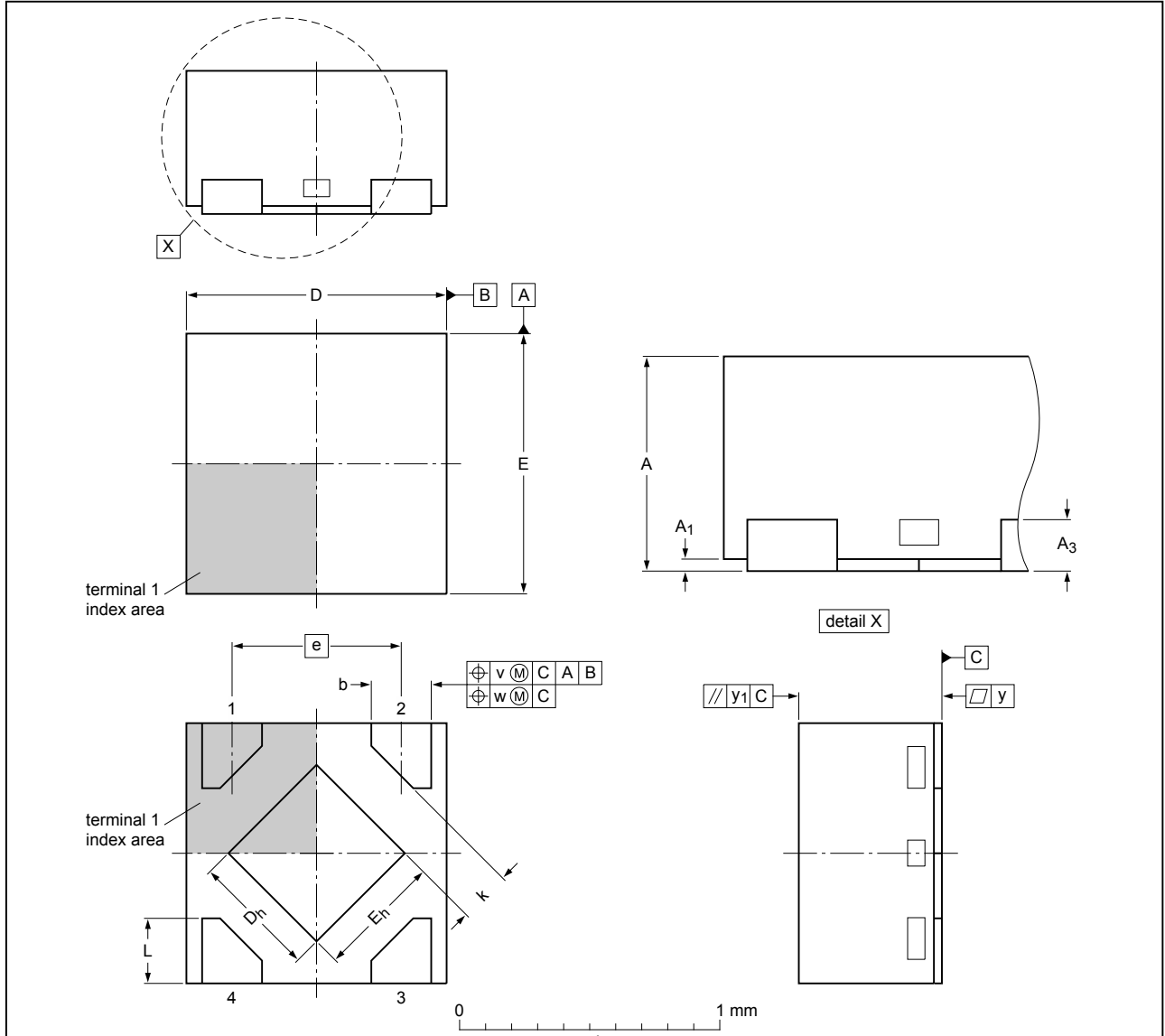
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.95	-	1	1.05	mm
E	package width	0.95	-	1	1.05	mm
A	seated height	-	-	-	0.55	mm
A ₂	package height	-	-	-	-	
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	4	-	



2. Package outline

Plastic thermal enhanced ultra thin small outline package; no leads;
4 terminals; body 1 x 1 x 0.55 mm

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Dimensions

Unit ⁽¹⁾	A	A ₁	A ₃	b	D	D _h	E	E _h	e	k	L	v	w	y	y ₁
max	0.55	0.05	0.152	0.30	1.05	0.53	1.05	0.53			0.30				
mm nom				0.25	1.00	0.48	1.00	0.48	0.65		0.25	0.1	0.05	0.05	0.05
min		0.00	0.05	0.20	0.95	0.43	0.95	0.43		0.2	0.20				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1194-1_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1194-1	---	---	---		41-05-30- 12-05-22

Fig. 1. Package outline DFN1010C-4 (SOT1194-1)

3. Soldering

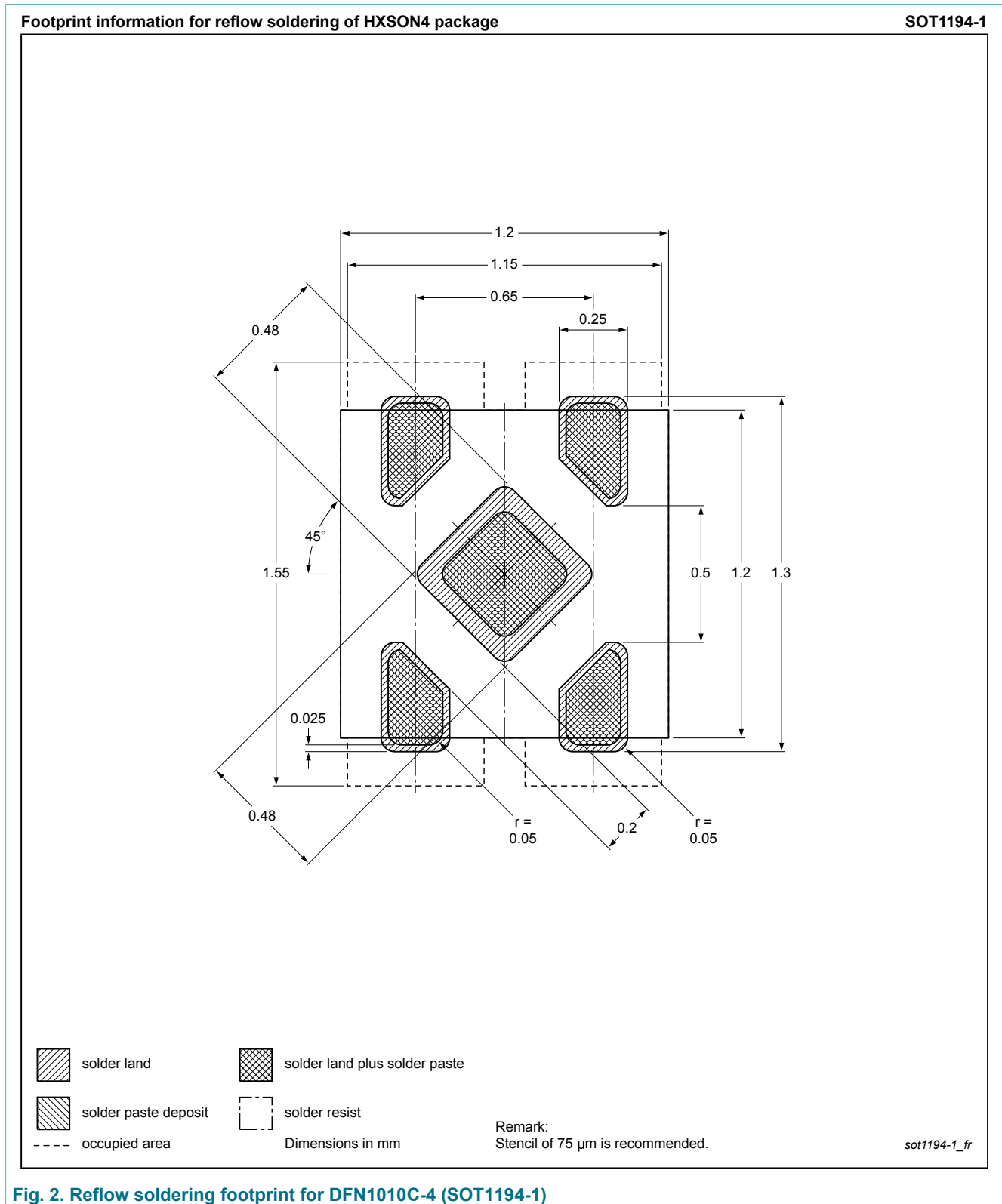


Fig. 2. Reflow soldering footprint for DFN1010C-4 (SOT1194-1)

4. Legal information

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